



## Film Capacitors

### EMI Suppression Capacitors (MKP)

**Series/Type:** B32911 ... B32916

**Date:** February 2013

### Typical applications

- X1 class for interference suppression
- "Across the line" applications
- For apparatus permanently connected to mains and isolated from direct contact with humidity

### Climatic

- Max. operating temperature: 110 °C
- Climatic category (IEC 60068-1): 40/110/56

### Construction

- Dielectric: polypropylene (MKP)
- Plastic case (UL 94 V-0)
- Epoxy resin sealing (UL 94 V-0)

### Features

- Very small dimensions
- Good self-healing properties
- High voltage capability
- RoHS-compatible
- Halogen-free capacitors available on request

### Terminals

- Parallel wire leads, lead-free tinned
- Special lead lengths available on request

### Marking

Manufacturer's logo, lot number, date code, rated capacitance (coded), capacitance tolerance (code letter), rated AC voltage (IEC), series number, sub-class (X1), dielectric code (MKP), climatic category, passive flammability category, approvals.

### Delivery mode

Bulk (untaped)  
 Taped (Ammo pack or reel)  
 For taping details, refer to chapter "Taping and packing".

### Dimensional drawing



Dimensions in mm

Lead spacing $e \pm 0.4$	Lead diameter $d_1$	Type
10	0.6	B32911
15 ... 27.5	0.8	B32912 ... B32914
37.5	1.0	B32916

### Marking examples

$e = 10$  mm



KMK1261-Z

$15 \leq e \leq 27.5$  mm  
 $(C_R \leq 1 \mu F)$



KMK1262-P

$22.5 \leq e \leq 37.5$  mm  
 $(C_R > 1 \mu F)$



KMK1263-7



## Approvals

Approval marks	Standards	Certificate
	EN 60384-14 / IEC 60384-14 (330 V AC)	40032766
	UL1414 (250 V AC) UL1283 (300 V AC)	E97863 E157153
 <sup>1)</sup>	CSA C22.2 No. 1 (250 V AC) CSA C22.2 No. 8 (300 V AC)	E97863 E157153

1) approved by UL

## Overview of available types

Lead spacing	10 mm	15 mm	22.5 mm	27.5 mm	37.5 mm
Type	B32911	B32912	B32913	B32914	B32916
$C_R$ ( $\mu$ F)					
0.010					
0.022					
0.033					
0.047					
0.068					
0.10					
0.15					
0.22					
0.33					
0.47					
0.68					
1.0					
1.5					
2.2					
3.3					
4.7					
6.8					



**B32911 ... B32916**

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**Ordering codes and packing units**

Lead spacing mm	C <sub>R</sub> μF	Max. dimensions w × h × l mm	Ordering code (composition see below)	Ammo pack pcs./MOQ	Reel pcs./MOQ	Untaped pcs./MOQ
10	0.010	4.0 × 9.0 × 13.0	B32911A3103+***	4000	6800	4000
	0.022	5.0 × 11.0 × 13.0	B32911B3223+***	3320	5200	4000
	0.033	6.0 × 12.0 × 13.0	B32911A3333M***	2720	4400	4000
15	0.022	5.0 × 10.5 × 18.0	B32912A3223+***	4680	5200	4000
	0.033	5.0 × 10.5 × 18.0	B32912A3333+***	4680	5200	4000
	0.047	5.0 × 10.5 × 18.0	B32912A3473+***	4680	5200	4000
	0.068	6.0 × 11.0 × 18.0	B32912A3683+***	3840	4400	4000
	0.10	7.0 × 12.5 × 18.0	B32912A3104+***	3320	3600	4000
	0.15	7.0 × 12.5 × 18.0	B32912B3154M***	3320	3600	4000
	0.15	8.5 × 14.5 × 18.0	B32912A3154+***	2720	2800	2000
	0.22	8.5 × 14.5 × 18.0	B32912B3224M***	2720	2800	2000
	0.22	9.0 × 17.5 × 18.0	B32912A3224+***	2560	2800	2000
	0.33	9.0 × 17.5 × 18.0	B32912B3334M***	2560	2800	2000
22.5	0.15	6.0 × 15.0 × 26.5	B32913A3154+***	2720	2800	2880
	0.22	7.0 × 16.0 × 26.5	B32913A3224+***	2320	2400	2520
	0.33	8.5 × 16.5 × 26.5	B32913A3334M***	1920	2000	2040
	0.47	10.5 × 18.5 × 26.5	B32913A3474M***	1560	1600	2160
27.5	0.47	11.0 × 21.0 × 31.5	B32914A3474+***	–	1400	1280
	0.68	11.0 × 21.0 × 31.5	B32914B3684+***	–	1400	1280
	1.0	13.5 × 23.0 × 31.5	B32914A3105+***	–	1000	1040
	1.5	18.0 × 27.5 × 31.5	B32914A3155+***	–	–	800
	2.2	19.0 × 30.0 × 31.5	B32914A3225M***	–	–	720
37.5	3.3	18.0 × 32.5 × 41.5	B32916A3335M***	–	–	720
	4.7	20.0 × 39.5 × 41.5	B32916A3475M***	–	–	640
	6.8	28.0 × 42.5 × 41.5	B32916A3685M***	–	–	440

MOQ = Minimum Order Quantity, consisting of 4 packing units.

Further intermediate capacitance values on request.

**Composition of ordering code**

+ = Capacitance tolerance code:

M = ±20%

K = ±10%

\*\*\* = Packaging code:

289 = Ammo pack

189 = Reel

000 = Untaped (lead length 6 – 1 mm)

### Technical data

Rated AC voltage ( IEC 60384-14 )	330 V (50/60 Hz)		
Maximum continuous DC voltage $V_{DC}$	760 V		
Max. operating temperature $T_{op,max}$	+110 °C		
DC test voltage	2500 V, 2 s		
Dissipation factor $\tan \delta$ (in $10^{-3}$ ) at 20 °C (upper limit values)		$C_R \leq 2.2 \mu F$	$C_R > 2.2 \mu F$
	at 1 kHz	1	2
Insulation resistance $R_{ins}$ or time constant $\tau = C_R \cdot R_{ins}$ at 100 V DC, 20 °C, rel. humidity $\leq 65\%$ and for 60 s (minimum as-delivered values)		$C_R \leq 0.33 \mu F$	$C_R > 0.33 \mu F$
		100 000 M $\Omega$	30 000 s
Passive flammability category to IEC 40 (CO) 752	B		
Capacitance tolerances (measured at 1 kHz)	$\pm 10\%$ (K), $\pm 20\%$ (M)		

### Pulse handling capability

"dV/dt" represents the maximum permissible voltage change per unit of time for non-sinusoidal voltages, expressed in V/ $\mu$ s.

" $k_0$ " represents the maximum permissible pulse characteristic of the waveform applied to the capacitor, expressed in V<sup>2</sup>/ $\mu$ s.

*Note:*

*The values of dV/dt and  $k_0$  provided below must not be exceeded in order to avoid damaging the capacitor.*

### dV/dt and $k_0$ values

Lead spacing	10 mm	15 mm	22.5 mm	27.5 mm	37.5 mm
dV/dt in V/ $\mu$ s	550	400	200	150	100
$k_0$ in V <sup>2</sup> / $\mu$ s	473 000	344 000	172 000	129 000	86 000



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**X1 / 330 V AC**

## Mounting guidelines

### 1 Soldering

#### 1.1 Solderability of leads

The solderability of terminal leads is tested to IEC 60068-2-20, test Ta, method 1.

Before a solderability test is carried out, terminals are subjected to accelerated ageing (to IEC 60068-2-2, test Ba: 4 h exposure to dry heat at 155 °C). Since the ageing temperature is far higher than the upper category temperature of the capacitors, the terminal wires should be cut off from the capacitor before the ageing procedure to prevent the solderability being impaired by the products of any capacitor decomposition that might occur.

Solder bath temperature	235 ±5 °C
Soldering time	2.0 ±0.5 s
Immersion depth	2.0 +0/-0.5 mm from capacitor body or seating plane
Evaluation criteria:	
Visual inspection	Wetting of wire surface by new solder ≥90%, free-flowing solder

#### 1.2 Resistance to soldering heat

Resistance to soldering heat is tested to IEC 60068-2-20, test Tb, method 1A.

Conditions:

Series	Solder bath temperature	Soldering time
MKT boxed (except 2.5 × 6.5 × 7.2 mm) coated uncoated (lead spacing > 10 mm)	260 ±5 °C	10 ±1 s
MFP MKP (lead spacing > 7.5 mm)		
MKT boxed (case 2.5 × 6.5 × 7.2 mm)		5 ±1 s
MKP (lead spacing ≤ 7.5 mm)		< 4 s
MKT uncoated (lead spacing ≤ 10 mm) insulated (B32559)		recommended soldering profile for MKT uncoated (lead spacing ≤ 10 mm) and insulated (B32559)



Immersion depth	2.0 +0/−0.5 mm from capacitor body or seating plane
Shield	Heat-absorbing board, (1.5 ±0.5) mm thick, between capacitor body and liquid solder
Evaluation criteria:	
Visual inspection	No visible damage
$\Delta C/C_0$	2% for MKT/MKP/MFP 5% for EMI suppression capacitors
$\tan \delta$	As specified in sectional specification



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### 1.3 General notes on soldering

Permissible heat exposure loads on film capacitors are primarily characterized by the upper category temperature  $T_{max}$ . Long exposure to temperatures above this type-related temperature limit can lead to changes in the plastic dielectric and thus change irreversibly a capacitor's electrical characteristics. For short exposures (as in practical soldering processes) the heat load (and thus the possible effects on a capacitor) will also depend on other factors like:

- Pre-heating temperature and time
- Forced cooling immediately after soldering
- Terminal characteristics:
  - diameter, length, thermal resistance, special configurations (e.g. crimping)
- Height of capacitor above solder bath
- Shadowing by neighboring components
- Additional heating due to heat dissipation by neighboring components
- Use of solder-resist coatings

The overheating associated with some of these factors can usually be reduced by suitable countermeasures. For example, if a pre-heating step cannot be avoided, an additional or reinforced cooling process may possibly have to be included.

EPCOS recommends the following conditions:

- Pre-heating with a maximum temperature of 110 °C
- Temperature inside the capacitor should not exceed the following limits:
  - MKP/MFP 110 °C
  - MKT 160 °C
- When SMD components are used together with leaded ones, the leaded film capacitors should not pass into the SMD adhesive curing oven. The leaded components should be assembled after the SMD curing step.
- Leaded film capacitors are not suitable for reflow soldering.

#### Uncoated capacitors

For uncoated MKT capacitors with lead spacings  $\leq 10$  mm (B32560/B32561) the following measures are recommended:

- pre-heating to not more than 110 °C in the preheater phase
- rapid cooling after soldering





### Cautions and warnings

- Do not exceed the upper category temperature (UCT).
- Do not apply any mechanical stress to the capacitor terminals.
- Avoid any compressive, tensile or flexural stress.
- Do not move the capacitor after it has been soldered to the PC board.
- Do not pick up the PC board by the soldered capacitor.
- Do not place the capacitor on a PC board whose PTH hole spacing differs from the specified lead spacing.
- Do not exceed the specified time or temperature limits during soldering.
- Avoid external energy inputs, such as fire or electricity.
- Avoid overload of the capacitors.

The table below summarizes the safety instructions that must always be observed. A detailed description can be found in the relevant sections of the chapters "General technical information" and "Mounting guidelines".

Topic	Safety information	Reference chapter "General technical information"
Storage conditions	Make sure that capacitors are stored within the specified range of time, temperature and humidity conditions.	4.5 "Storage conditions"
Flammability	Avoid external energy, such as fire or electricity (passive flammability), avoid overload of the capacitors (active flammability) and consider the flammability of materials.	5.3 "Flammability"
Resistance to vibration	Do not exceed the tested ability to withstand vibration. The capacitors are tested to IEC 60068-2-6. EPCOS offers film capacitors specially designed for operation under more severe vibration regimes such as those found in automotive applications. Consult our catalog "Film Capacitors for Automotive Electronics".	5.2 "Resistance to vibration"


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Topic	Safety information	Reference chapter "Mounting guidelines"
Soldering	Do not exceed the specified time or temperature limits during soldering.	1 "Soldering"
Cleaning	Use only suitable solvents for cleaning capacitors.	2 "Cleaning"
Embedding of capacitors in finished assemblies	When embedding finished circuit assemblies in plastic resins, chemical and thermal influences must be taken into account. Caution: Consult us first, if you also wish to embed other uncoated component types!	3 "Embedding of capacitors in finished assemblies"

### Design of EMI Capacitors

EPCOS EMI capacitors use polypropylene (PP) film metalized with a thin layer of Zinc (Zn). The following key points have made this design suitable to IEC/UL testing, holding a minimum size.

- Overvoltage AC capability with very high temperature Endurance test of IEC60384-14 (3<sup>rd</sup> edition, 2005-07) / UL60384-14 (1st edition, 2009-04) must be performed at  $1.25 \times V_R$  at maximum temperature, during 1000 hours, with a capacitance drift less than 10%.
- Higher breakdown voltage withstanding if compared to other film metallizations, like Aluminum. IEC60384-14 (3<sup>rd</sup> edition, 2005-07) / UL60384-14 (1st edition, 2009-04) establishes high voltage tests performed at  $4.3 \times V_R - 1$  minute, impulse testing at 2500 V for  $C = 1 \mu\text{F}$  and active flammability tests.
- Damp heat steady state: 40 °C/ 93% RH / 56 days. (without voltage or current load)

### Effect of humidity on capacitance stability

Long contact of a film capacitor with humidity can produce irreversible effects. Direct contact with liquid water or excess exposure to high ambient humidity or dew will eventually remove the film metallization and thus destroy the capacitor. Plastic boxed capacitors must be properly tested in the final application at the worst expected conditions of temperature and humidity in order to check if any parameter drift may provoke a circuit malfunction.

In case of penetration of humidity through the film, the layer of Zinc can be degraded, specially under AC operation (change of polarity), accelerated by the temperature, provoking an increment of the serial resistance of the electrode and eventually a reduction of the capacitance value. For DC operation, the parameter drift is much less.

Plastic boxes and resins can not protect 100% against humidity. Metal enclosures, resin potting or coatings or similar measures by customers in their applications will offer additional protection against humidity penetration.

**Symbols and terms**

Symbol	English	German
$\alpha$	Heat transfer coefficient	Wärmeübergangszahl
$\alpha_C$	Temperature coefficient of capacitance	Temperaturkoeffizient der Kapazität
A	Capacitor surface area	Kondensatoroberfläche
$\beta_C$	Humidity coefficient of capacitance	Feuchtekoeffizient der Kapazität
C	Capacitance	Kapazität
$C_R$	Rated capacitance	Nennkapazität
$\Delta C$	Absolute capacitance change	Absolute Kapazitätsänderung
$\Delta C/C$	Relative capacitance change (relative deviation of actual value)	Relative Kapazitätsänderung (relative Abweichung vom Ist-Wert)
$\Delta C/C_R$	Capacitance tolerance (relative deviation from rated capacitance)	Kapazitätstoleranz (relative Abweichung vom Nennwert)
dt	Time differential	Differentielle Zeit
$\Delta t$	Time interval	Zeitintervall
$\Delta T$	Absolute temperature change (self-heating)	Absolute Temperaturänderung (Selbsterwärmung)
$\Delta \tan \delta$	Absolute change of dissipation factor	Absolute Änderung des Verlustfaktors
$\Delta V$	Absolute voltage change	Absolute Spannungsänderung
dV/dt	Time differential of voltage function (rate of voltage rise)	Differentielle Spannungsänderung (Spannungsflankensteilheit)
$\Delta V/\Delta t$	Voltage change per time interval	Spannungsänderung pro Zeitintervall
E	Activation energy for diffusion	Aktivierungsenergie zur Diffusion
ESL	Self-inductance	Eigeninduktivität
ESR	Equivalent series resistance	Ersatz-Serienwiderstand
f	Frequency	Frequenz
$f_1$	Frequency limit for reducing permissible AC voltage due to thermal limits	Grenzfrequenz für thermisch bedingte Reduzierung der zulässigen Wechselspannung
$f_2$	Frequency limit for reducing permissible AC voltage due to current limit	Grenzfrequenz für strombedingte Reduzierung der zulässigen Wechselspannung
$f_r$	Resonant frequency	Resonanzfrequenz
$F_D$	Thermal acceleration factor for diffusion	Therm. Beschleunigungsfaktor zur Diffusion
$F_T$	Derating factor	Deratingfaktor
i	Current (peak)	Stromspitze
$I_C$	Category current (max. continuous current)	Kategoriestrom (max. Dauerstrom)



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Symbol	English	German
$I_{RMS}$	(Sinusoidal) alternating current, root-mean-square value	(Sinusförmiger) Wechselstrom
$i_z$	Capacitance drift	Inkonstanz der Kapazität
$k_0$	Pulse characteristic	Impulskennwert
$L_S$	Series inductance	Serieninduktivität
$\lambda$	Failure rate	Ausfallrate
$\lambda_0$	Constant failure rate during useful service life	Konstante Ausfallrate in der Nutzungsphase
$\lambda_{test}$	Failure rate, determined by tests	Experimentell ermittelte Ausfallrate
$P_{diss}$	Dissipated power	Abgegebene Verlustleistung
$P_{gen}$	Generated power	Erzeugte Verlustleistung
$Q$	Heat energy	Wärmeenergie
$\rho$	Density of water vapor in air	Dichte von Wasserdampf in Luft
$R$	Universal molar constant for gases	Allg. Molarkonstante für Gas
$R$	Ohmic resistance of discharge circuit	Ohmscher Widerstand des Entladekreises
$R_i$	Internal resistance	Innenwiderstand
$R_{ins}$	Insulation resistance	Isolationswiderstand
$R_P$	Parallel resistance	Parallelwiderstand
$R_S$	Series resistance	Serienwiderstand
$S$	severity (humidity test)	Schärfegrad (Feuchtest)
$t$	Time	Zeit
$T$	Temperature	Temperatur
$\tau$	Time constant	Zeitkonstante
$\tan \delta$	Dissipation factor	Verlustfaktor
$\tan \delta_D$	Dielectric component of dissipation factor	Dielektrischer Anteil des Verlustfaktors
$\tan \delta_P$	Parallel component of dissipation factor	Parallelanteil des Verlustfaktors
$\tan \delta_S$	Series component of dissipation factor	Serienanteil des Verlustfaktors
$T_A$	Ambient temperature	Umgebungstemperatur
$T_{max}$	Upper category temperature	Obere Kategorietemperatur
$T_{min}$	Lower category temperature	Untere Kategorietemperatur
$t_{OL}$	Operating life at operating temperature and voltage	Betriebszeit bei Betriebstemperatur und -spannung
$T_{op}$	Operating temperature	Betriebstemperatur
$T_R$	Rated temperature	Nenntemperatur
$T_{ref}$	Reference temperature	Referenztemperatur
$t_{SL}$	Reference service life	Referenz-Lebensdauer
$V_{AC}$	AC voltage	Wechselspannung

Symbol	English	German
$V_C$	Category voltage	Kategorie <span>­</span> spannung
$V_{C,RMS}$	Category AC voltage	(Sinusförmige) Kategorie-Wechselspannung
$V_{CD}$	Corona-discharge onset voltage	Teilentlade-Einsatzspannung
$V_{ch}$	Charging voltage	Ladespannung
$V_{DC}$	DC voltage	Gleichspannung
$V_{FB}$	Fly-back capacitor voltage	Spannung (Flyback)
$V_i$	Input voltage	Eingangsspannung
$V_o$	Output voltage	Ausgangssspannung
$V_{op}$	Operating voltage	Betriebsspannung
$V_p$	Peak pulse voltage	Impuls-Spitzen <span>­</span> spannung
$V_{pp}$	Peak-to-peak voltage Impedance	Spannungshub
$V_R$	Rated voltage	Nennspannung
$\hat{V}_R$	Amplitude of rated AC voltage	Amplitude der Nenn-Wechselspannung
$V_{RMS}$	(Sinusoidal) alternating voltage, root-mean-square value	(Sinusförmige) Wechselspannung
$V_{SC}$	S-correction voltage	Spannung bei Anwendung "S-correction"
$V_{sn}$	Snubber capacitor voltage	Spannung bei Anwendung "Beschaltung"
$Z$	Impedance	Schein <span>­</span> widerstand
$e$	Lead spacing	Rastermaß

## Important notes

The following applies to all products named in this publication:

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